

PRESS RELEASE

**LoRaWAN World Expo: HT Micron presents new LoRa® and Bluetooth® IoT chip made in Brazil**

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HT Micron proudly introduces the new LoRa® and Bluetooth® IoT chip made in Brazil at the LoRaWAN World Expo in Paris. The iMCP HTLRBL32L, a system-in-package of 13x13x1.1 mm, enables easy integration and prototyping of long- and short-range solutions for the Internet of Things.

“LoRaWAN® connectivity is being adopted worldwide in all segments of the Internet of Things. We see exciting use cases and massive deployments in smart metering, asset tracking, condition monitoring, industry 4.0, smart cities and many more. Bluetooth® is already widely used for short range communication. Therefore, the combination of both LoRa® and Bluetooth® in one single SiP brings huge benefits to IoT developers and solution integrators” says Edelweis Ritt, Chief Officer of Institutional Relations and Strategic Partnerships at HT Micron.

HT Micron, a Brazilian manufacturer of advanced semiconductor solutions, is participating and exhibiting at the LoRaWAN World Expo for the first time. The biggest official LoRaWAN® event takes place in Paris, France from July 6-7.

“The vibrant LoRa Alliance® ecosystem brings together companies from the IoT value chain and complementary technologies. We are excited about the LoRaWAN World Expo, meeting many new partners and customers and discussing use cases and opportunities.” highlights Julio Soccol, Sales and Marketing manager.

At booth no. 63, visitors will see the new iMCP HTLRBL32L SiP in action. While ready to send user data in multi-region LoRaWAN® applications, the Bluetooth® connectivity enables easy device commissioning, wireless firmware update and mesh networking capabilities. The full product brief will be released on HT Micron’s Github page.

Samples of the iMCP HTLRBL32L are expected for September 2022. Orders for mass production can be placed starting from Q3/2022.

An additional highlight is the IPv6 over LoRaWAN® demo in collaboration with Acklio at the demo pod area. The LoRa Alliance® has recently released its Technical Specification TS010 on the IPv6 Adaptation Layer, which facilitates the development of secure and interoperable applications over LoRaWAN®. Now protocol data from IP-based solutions is made transportable over LoRaWAN®, using the SCHC header compression and fragmentation mechanism standardized by the IETF. The IPv6 over LoRaWAN® demo features Acklio’s software suite and HT Micron’s custom embedded firmware package for SCHC which is already available for the iMCP HTLRBL32L.

“HT Micron is very proud to offer the SiP with LoRa® and Bluetooth® made in Brazil to IoT developers, device makers and solution integrators worldwide. The iMCP HTLRBR32L with accessible MCU and full range of peripheral interfaces will be appreciated for its high

configurability and flexibility”, says Edelweis Ritt. “Our goal is to simplify integration and accelerate the development of IoT solutions as much as possible. This saves customer NRE and valuable time to market on the path to massive IoT deployments.”

For more information contact: [imcp@htmicron.com.br](mailto:imcp@htmicron.com.br) | Mr. Julio Soccol

#### About HT Micron Semicondutores S.A.

HT Micron provides advanced semiconductor products. The portfolio includes memories for computers, mobile phones and smart TVs, as well as System-in-Package connectivity solutions for the Internet of Things. HT Micron is a Brazilian company, having as main shareholder the South Korean group HANA Micron, and is based in the city of São Leopoldo, RS, in Brazil. More on <http://www.htmicron.com.br/en/>. HT Micron is a member of the LoRa Alliance®.

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